

PATENT ASSIGNMENT

Electronic Version v1.1
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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Lawrence A. Clevenger</td> <td>07/18/2013</td> </tr> <tr> <td>Carl Radens</td> <td>08/02/2013</td> </tr> <tr> <td>Yiheng Xu</td> <td>07/18/2013</td> </tr> <tr> <td>Edem Wornyo</td> <td>07/22/2013</td> </tr> </tbody> </table>		Name	Execution Date	Lawrence A. Clevenger	07/18/2013	Carl Radens	08/02/2013	Yiheng Xu	07/18/2013	Edem Wornyo	07/22/2013
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RECEIVING PARTY DATA											
<table border="1"> <tr> <td>Name:</td> <td>International Business Machines Corporation</td> </tr> <tr> <td>Street Address:</td> <td>New Orchard Road</td> </tr> <tr> <td>City:</td> <td>Armonk</td> </tr> <tr> <td>State/Country:</td> <td>NEW YORK</td> </tr> <tr> <td>Postal Code:</td> <td>10504</td> </tr> </table>		Name:	International Business Machines Corporation	Street Address:	New Orchard Road	City:	Armonk	State/Country:	NEW YORK	Postal Code:	10504
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PROPERTY NUMBERS Total: 1											
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13931688</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13931688						
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CORRESPONDENCE DATA											
<p>Fax Number: 2066826031 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 206-622-4900 Email: KyleH@SeedIP.com Correspondent Name: Hayley J. Talbert Address Line 1: 701 Fifth Avenue Address Line 2: Suite 5400 Address Line 4: Seattle, WASHINGTON 98104</p>											
ATTORNEY DOCKET NUMBER:	850063.690										
NAME OF SUBMITTER:	Hayley J. Talbert										
Signature:	/Hayley J. Talbert/										

PATENT

Date:

09/26/2013

Total Attachments: 4

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**DECLARATION (37 C.F.R. 1.63) FOR UTILITY PATENT APPLICATION USING AN
APPLICATION DATA SHEET (37 C.F.R. 1.76) AND ASSIGNMENT**

Title of Invention: THROUGH SILICON VIA STRUCTURE FOR INTERNAL CHIP COOLING

As a below named and undersigned inventor, I hereby declare that:

This declaration is directed to the attached application, or (if following box is checked):

☒ United States application or PCT international application number 13/931,688 filed on June 28, 2013.

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I have reviewed and understand the contents of the application, including the claims.

I am aware of the duty to disclose to the United States Patent and Trademark Office all information known to me to be material to patentability as defined in 37 CFR Section 1.56.

Whereas, I have made certain inventions, improvements, and discoveries (herein referred to as the "Invention") disclosed in the above-identified patent application and further identified by the IBM Docket Number provided above in the header of this document;

Whereas, International Business Machines Corporation, a corporation of New York having a place of business at Armonk, New York (herein referred to as "IBM"), desires to acquire, and I desire to grant to IBM, my entire worldwide right, title, and interest in and to the Invention and in and to any and all patent applications and patents directed thereto;

Now, therefore, for good and valuable consideration, the receipt and sufficiency thereof being hereby acknowledged, I ("ASSIGNOR") hereby sell or have sold, assign or have assigned, and otherwise transfer or have transferred to IBM (the "ASSIGNEE"), its successors, legal representatives, and assigns, my entire worldwide right, title, and interest in and to the Invention, the above-identified United States patent application, and any and all other patent applications and patents for the Invention which may be applied for or granted therefor in the United States and in all foreign countries and jurisdictions, including all divisions, continuations, reissues, reexaminations, renewals, extensions, counterparts, substitutes, and extensions thereof, and all rights of priority resulting from the filing of such applications and granting of such patents. In addition, I hereby authorize and request the Director of the United States Patent and Trademark Office to issue any United States Patent, and foreign patent authorities to issue any foreign patent, granted for the Invention, to IBM, its successors, legal representatives, and assigns, my entire worldwide right, title, and interest in and to the same to be held and enjoyed by IBM, its successors, legal representatives, and assigns to the full end of the terms for which any and all such patents may be granted, as fully and entirely as would have been held and enjoyed by me had this Assignment not been made; and I agree to execute any and all documents and instruments and perform all lawful acts reasonably related to recording this Assignment or perfecting title to the Invention and all related patents and applications, in IBM, its successors, legal representatives, and assigns, whenever requested by IBM, its successors, legal representatives, or assigns.

I acknowledge my prior and ongoing obligations to sell, assign, and transfer my rights under this

Assignment to IBM and am unaware of any reason why I may not have the full and unencumbered right to sell, assign, and transfer my rights hereby sold, assigned, and transferred, and have not executed, and will not execute, any document or instrument in conflict herewith. I also hereby grant IBM, its successors, legal representatives, and assigns, the right to insert in this Assignment any further identification (including, but not limited to, patent Application Number) which may be necessary or desirable for recordation of this Assignment. This Assignment is governed by the substantive laws of the State of New York, and any disputes will be resolved in a New York state court or federal court sited in New York.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

(1) Legal Name of Inventor: LAWRENCE A. CLEVINGER

Signature: Lawrence A. Clevinger Date: 7/18/2013

(2) Legal Name of Inventor: CARL RADENS

Signature: Carl Radens Date: 8/2/13

(3) Legal Name of Inventor: YIHENG XU

Signature: Yiheng Xu Date: 7/18/2013

(4) Legal Name of Inventor: EDEM WORNYO

Signature: _____ Date: _____

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Whereas, International Business Machines Corporation, a corporation of New York having a place of business at Armonk, New York (herein referred to as "IBM"), desires to acquire, and I desire to grant to IBM, my entire worldwide right, title, and interest in and to the Invention and in and to any and all patent applications and patents directed thereto;

Now, therefore, for good and valuable consideration, the receipt and sufficiency thereof being hereby acknowledged, I ("ASSIGNOR") hereby sell or have sold, assign or have assigned, and otherwise transfer or have transferred to IBM (the "ASSIGNEE"), its successors, legal representatives, and assigns, my entire worldwide right, title, and interest in and to the Invention, the above-identified United States patent application, and any and all other patent applications and patents for the Invention which may be applied for or granted therefor in the United States and in all foreign countries and jurisdictions, including all divisions, continuations, reissues, reexaminations, renewals, extensions, counterparts, substitutes, and extensions thereof, and all rights of priority resulting from the filing of such applications and granting of such patents. In addition, I hereby authorize and request the Director of the United States Patent and Trademark Office to issue any United States Patent, and foreign patent authorities to issue any foreign patent, granted for the Invention, to IBM, its successors, legal representatives, and assigns, my entire worldwide right, title, and interest in and to the same to be held and enjoyed by IBM, its successors, legal representatives, and assigns to the full end of the terms for which any and all such patents may be granted, as fully and entirely as would have been held and enjoyed by me had this Assignment not been made; and I agree to execute any and all documents and instruments and perform all lawful acts reasonably related to recording this Assignment or perfecting title to the Invention and all related patents and applications, in IBM, its successors, legal representatives, and assigns, whenever requested by IBM, its successors, legal representatives, or assigns.

I acknowledge my prior and ongoing obligations to sell, assign, and transfer my rights under this

IBM DOCKET NUMBER: FIS820130388

Assignment to IBM and am unaware of any reason why I may not have the full and unencumbered right to sell, assign, and transfer my rights hereby sold, assigned, and transferred, and have not executed, and will not execute, any document or instrument in conflict herewith. I also hereby grant IBM, its successors, legal representatives, and assigns, the right to insert in this Assignment any further identification (including, but not limited to, patent Application Number) which may be necessary or desirable for recordation of this Assignment. This Assignment is governed by the substantive laws of the State of New York, and any disputes will be resolved in a New York state court or federal court sited in New York.

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(1) Legal Name of Inventor: LAWRENCE A. CLEVINGER

Signature: _____ Date: _____

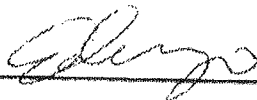
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Signature: _____ Date: _____

(3) Legal Name of Inventor: YIHENG XU

Signature: _____ Date: _____

(4) Legal Name of Inventor: EDEM WORNYO

Signature:  Date: 7/22/2013